

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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200mA, 30V Low VF SMD Schottky Barrier Diode

FEATURES

- Low capacitance
- Low forward voltage drop
- Moisture sensitivity level: level 1, per J-STD-020
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

ΔΙ	DDI	IC	ΔΤ	NS
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- Adapters
- For switching power supply
- Low stored charge
- Inverter

MECHANICAL DATA

- Case: SOD-523F
- Molding compound meets UL 94 V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 1.68 ± 0.5 mg

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	200	mA	
V_{RRM}	30	V	
I _{FSM}	1	Α	
V _F at I _F =200mA	0.6	V	
T _J Max.	125	°C	
Package	SOD-523F		
Configuration	Single die		







ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	RB520S-30	UNIT	
Marking code on the device		В		
Power dissipation	P _D	200	mW	
Repetitive peak reverse voltage	V_{RRM}	30	V	
Forward current	I _F	200	mA	
Non-repetitive peak forward surge current @ t = 8.3ms	I _{FSM}	1	Α	
Junction temperature range	T _J	-55 to +125	°C	
Storage temperature range	T _{STG}	-55 to +125	°C	

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	500	°C/W	



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ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	MIN	МАХ	UNIT
Forward voltage per diode (1)	$I_F = 200 \text{mA}, T_J = 25^{\circ}\text{C}$	V _F	-	0.6	V
Reverse breakdown voltage	I _R = 500 μA	$V_{(BR)}$	30	-	V
Reverse current (2)	V _R =10V, T _J = 25°C	I _R	-	1	μΑ

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION				
PART NO.	PACKAGE	PACKING		
RB520S-30 RKG	SOD-523F	3K / 7" Reel		
RB520S-30 RK	SOD-523F	3K / 7" Reel		
RB520S-30 RSG	SOD-523F	8K / 7" Reel		
RB520S-30 RS	SOD-523F	8K / 7" Reel		



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

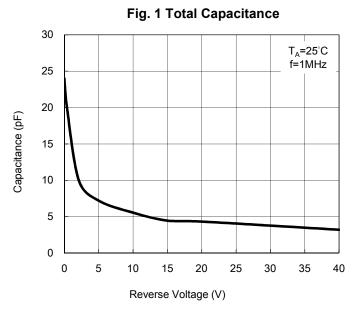
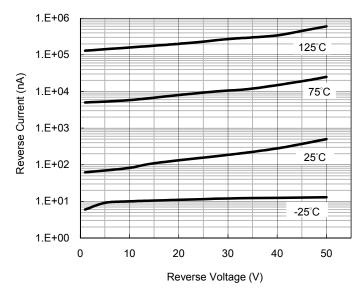


Fig. 2 Forward Voltage VS. Ambient 10000 1000 I_F, Forward Current (mA) 100 125°C 75°C 25°C 10 -25°C 1 0.1 0 200 400 600 800 1000 1200 V_F, Forward Voltage (mV)

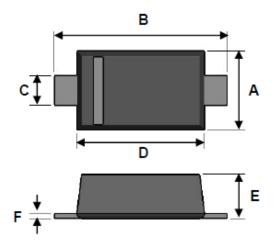
Fig. 3 Reverse Current VS. Reverse Voltage





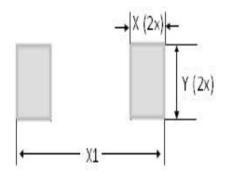
PACKAGE OUTLINE DIMENSION

SOD-523F



DIM	Unit (mm)		Unit (inch)		
DIM.	Min	Max	Min	Max	
Α	0.70	0.90	0.028	0.035	
В	1.50	1.70	0.059	0.067	
С	0.25	0.40	0.010	0.016	
D	1.10	1.30	0.043	0.051	
Е	0.50	0.77	0.020	0.030	
F	0.07	0.20	0.003	0.008	

SUGGEST PAD LAYOUT



DIM	Unit (mm)	Unit (inch)
DIM.	Тур.	Тур.
Х	0.60	0.024
X1	2.30	0.091
Y	0.80	0.031

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